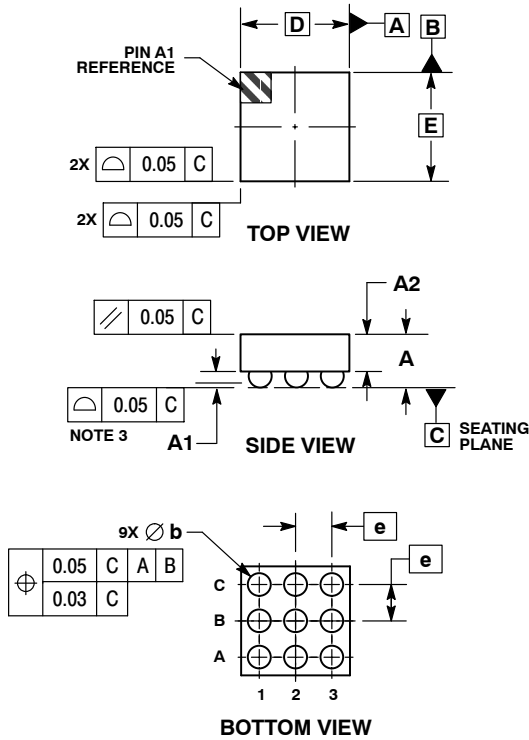




SCALE 4:1

WLCSP9, 1.22x1.22  
CASE 499BM  
ISSUE O

DATE 27 SEP 2010

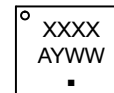


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	—	0.66
A1	0.17	0.24
A2	0.40 REF	
b	0.24	0.29
D	1.22 BSC	
E	1.22 BSC	
e	0.40 BSC	

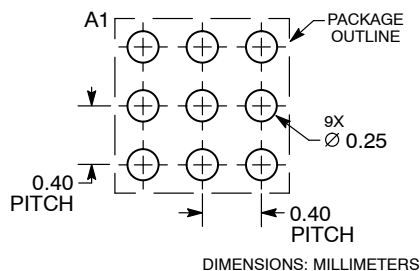
GENERIC  
MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "■", may or may not be present.

RECOMMENDED  
SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, [SOLDERRM/D](#).

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